

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP11612

REV: A

SVN REV: Not In VersionControl

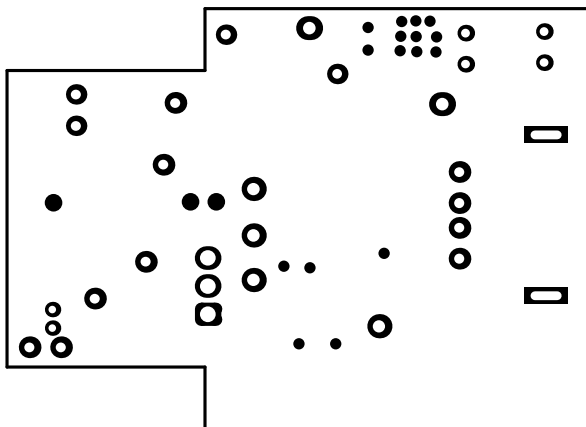
LAYER NAME = Top Overlay

TID #: PMP11612

PLOT NAME = Top Overlay

GENERATED : 3/31/2016 6:34:40 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

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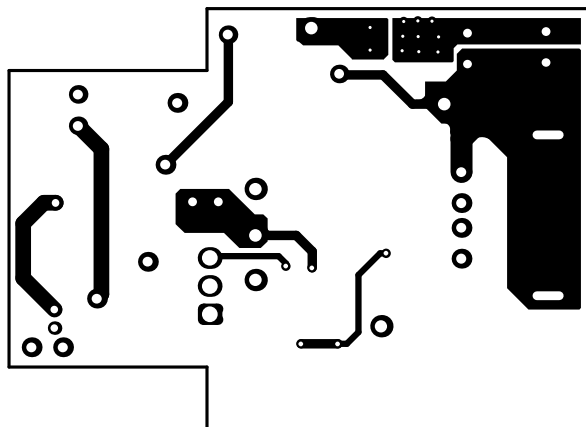
LAYER NAME = Top Solder

TID #: PMP11612

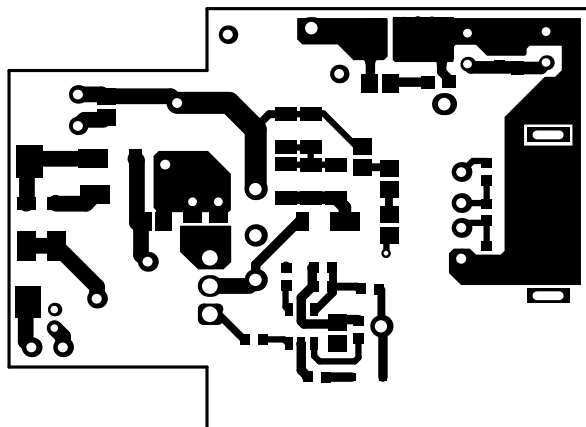
PLOT NAME = Top Solder Mask

GENERATED : 3/31/2016 6:34:41 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11612	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP11612		
PLOT NAME = Top Layer	GENERATED : 3/31/2016 6:34:41 PM	TEXAS INSTRUMENTS	



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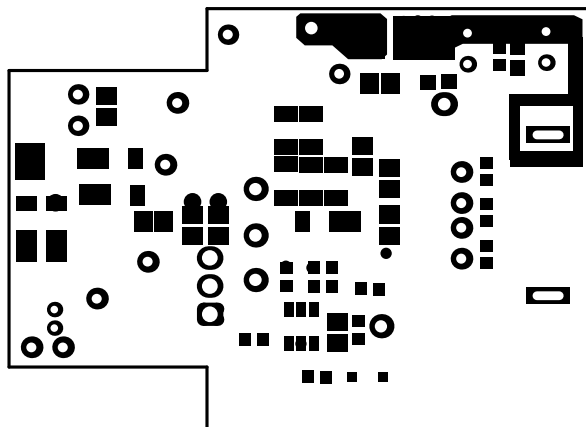
LAYER NAME = Bottom Layer

TID #: PMP11612

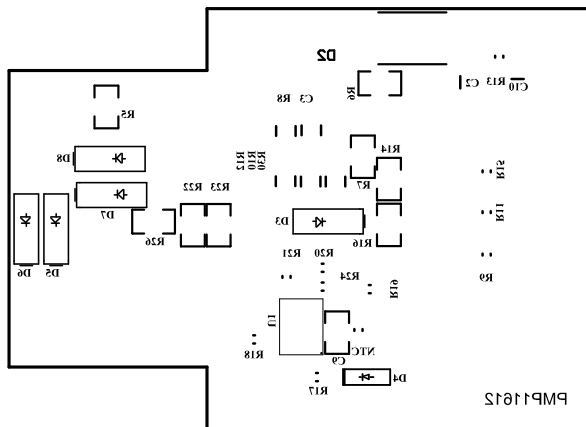
PLOT NAME = Bottom Layer

GENERATED : 3/31/2016 6:34:42 PM

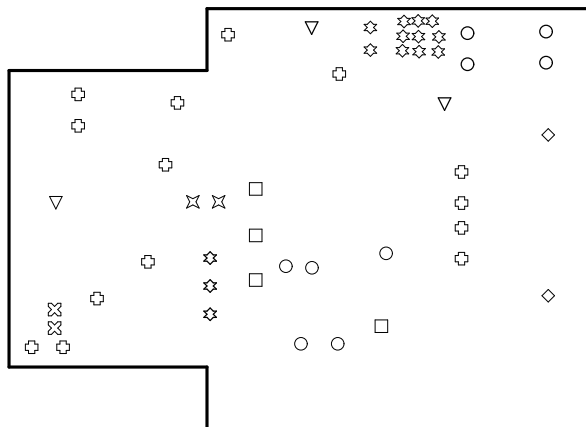
TEXAS INSTRUMENTS



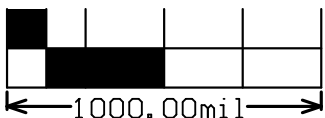
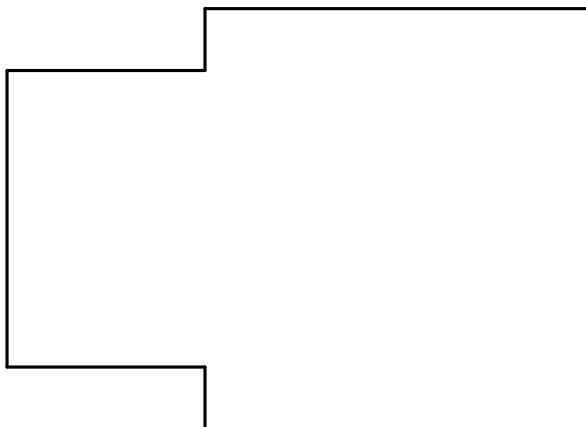
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11612	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP11612		
PLOT NAME = Bottom Solder Mask	GENERATED : 3/31/2016 6:34:43 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11612	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP11612		
PLOT NAME = Bottom Overlay	GENERATED : 3/31/2016	6:34:43 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11612	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP11612		
PLOT NAME = Drill Drawing	GENERATED : 3/31/2016 6:34:44 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11612	REV: A	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP11612		
PLOT NAME = Board Dimensions	GENERATED : 3/31/2016 6:34:45 PM	TEXAS INSTRUMENTS	

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